

Special Issue on
Conductive Polymer Composites: Preparation, Structure, Properties, and Applications

CALL FOR PAPERS

Conductive polymer composites (CPCs) are critical for applications in the fields of automotive, electronics, packaging, and aerospace, among others, because of their designability, low cost, and ease of processing when compared with metallic and ceramic counterparts.

Processing methods of interests include melt compounding, conventional injection molding, casting, calendaring, foaming, mixing, etc., as developed to prepare CPCs to address the application for the above industrial sectors. The properties of CPCs are determined by the distribution of fillers that can be affected by the types of fillers, processing conditions, host matrix, blending methods, etc. Relevant progress on modelling is also within the scope of the topic.

This Special Issue is dedicated to providing a forum for the preparation of CPCs with a special focus on state-of-the-art progress, structure design, development, and new trends. Original research and review articles are welcome.

Potential topics include but are not limited to the following:

- ▶ Processing of polymer composites
- ▶ Thermal interface materials
- ▶ Electrically conductive polymer compounds
- ▶ Thermally conducting polymer compounds
- ▶ Conductive fillers
- ▶ Modification of fillers
- ▶ Structural design
- ▶ Polymer blends
- ▶ Processing conditions
- ▶ Thermoplastic composites
- ▶ Thermosetting composites
- ▶ Foams
- ▶ Characterization methods
- ▶ Modelling
- ▶ Process-Structure-Properties

Authors can submit their manuscripts through the Manuscript Tracking System at <https://review.wiley.com/submit?specialIssue=499940>.

Papers are published upon acceptance, regardless of the Special Issue publication date.

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